

32-tap Digital Potentiometer (POT)

CAT5115

Description

The CAT5115 is a single digital POT designed as an electronic replacement for mechanical potentiometers and trim pots. Ideal for automated adjustments on high volume production lines, they are also well suited for applications where equipment requiring periodic adjustment is either difficult to access or located in a hazardous or remote environment.

The CAT5115 contains a 32-tap series resistor array connected between two terminals R_H and R_L . An up/down counter and decoder that are controlled by three input pins, determines which tap is connected to the wiper, R_W . The wiper is always set to the mid point, tap 15 at power up. The tap position is not stored in memory. Wiper-control of the CAT5115 is accomplished with three input control pins, \overline{CS} , U/ \overline{D} , and \overline{INC} . The \overline{INC} input increments the wiper in the direction which is determined by the logic state of the U/ \overline{D} input. The \overline{CS} input is used to select the device.

The digital POT can be used as a three-terminal resistive divider or as a two-terminal variable resistor. Digital POTs bring variability and programmability to a wide variety of applications including control, parameter adjustments, and signal processing.

For a pin-compatible device that recalls a stored tap position on power-up refer to the CAT5114 data sheet.

Features

- 32-position Linear Taper Potentiometer
- Low Power CMOS Technology
- Single Supply Operation: 2.5 V 6.0 V
- Increment Up/Down Serial Interface
- Resistance Values: $10 \text{ k}\Omega$, $50 \text{ k}\Omega$ and $100 \text{ k}\Omega$
- Available in PDIP, SOIC, TSSOP, MSOP Packages
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Automated Product Calibration
- Remote Control Adjustments
- Offset, Gain and Zero Control
- Tamper-proof Calibrations
- Contrast, Brightness and Volume Controls
- Motor Controls and Feedback Systems
- Programmable Analog Functions







MSOP-8 Z SUFFIX CASE 846AQ

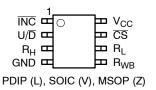


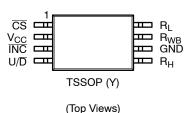
PDIP-8 L SUFFIX CASE 646AA



TSSOP-8 Y SUFFIX CASE 948AL

PIN CONFIGURATIONS





ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

FUNCTIONAL DIAGRAM

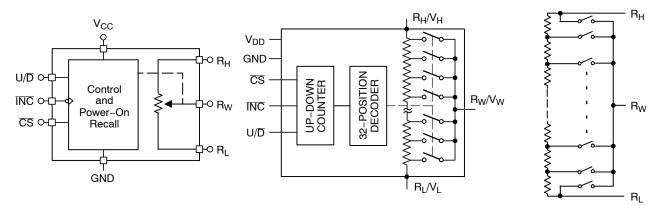


Figure 1. General

Figure 2. Detailed

Figure 3. Electronic Potentiometer Implementation

Table 1. PIN DESCRIPTIONS

Name	Function	
ĪNC	Increment Control	
U/D	Up/Down Control	
R _H	Potentiometer High Terminal	
GND	Ground	
R _W	Buffered Wiper Terminal	
R_L	Potentiometer Low Terminal	
CS	Chip Select	
V _{CC}	Supply Voltage	

PIN FUNCTION

INC: Increment Control Input

The \overline{INC} input moves the wiper in the up or down direction determined by the condition of the U/\overline{D} input.

U/**D**: Up/Down Control Input

The U/\overline{D} input controls the direction of the wiper movement. When in a high state and \overline{CS} is low, any high-to-low transition on \overline{INC} will cause the wiper to move one increment toward the R_H terminal. When in a low state and \overline{CS} is low, any high-to-low transition on \overline{INC} will cause the wiper to move one increment towards the R_L terminal.

RH: High End Potentiometer Terminal

 $R_{\rm H}$ is the high end terminal of the potentiometer. It is not required that this terminal be connected to a potential greater than the $R_{\rm L}$ terminal. Voltage applied to the $R_{\rm H}$ terminal cannot exceed the supply voltage, V_{CC} or go below ground, GND.

R_W: Wiper Potentiometer Terminal

 R_W is the wiper terminal of the potentiometer. Its position on the resistor array is controlled by the control inputs, \overline{INC} ,

 U/\overline{D} and \overline{CS} . Voltage applied to the R_W terminal cannot exceed the supply voltage, V_{CC} or go below ground, GND.

RL: Low End Potentiometer Terminal

 $R_{\rm L}$ is the low end terminal of the potentiometer. It is not required that this terminal be connected to a potential less than the $R_{\rm H}$ terminal. Voltage applied to the $R_{\rm L}$ terminal cannot exceed the supply voltage, $V_{\rm CC}$ or go below ground, GND. $R_{\rm L}$ and $R_{\rm H}$ are electrically interchangeable.

CS: Chip Select

The chip select input is used to activate the control input of the CAT5115 and is active low. When in a high state, activity on the $\overline{\text{INC}}$ and U/D inputs will not affect or change the position of the wiper.

DEVICE OPERATION

The CAT5115 operates like a digitally controlled potentiometer with R_H and R_L equivalent to the high and low terminals and R_W equivalent to the mechanical potentiometer's wiper. There are 32 available tap positions including the resistor end points, R_H and R_L . There are 31 resistor elements connected in series between the R_H and R_L terminals. The wiper terminal is connected to one of the 32 taps and controlled by three inputs, $\overline{\rm INC}$, U/ $\overline{\rm D}$ and $\overline{\rm CS}$. These inputs control a five-bit up/down counter whose output is decoded to select the wiper position.

With $\overline{\text{CS}}$ set LOW the CAT5115 is selected and will respond to the U/ $\overline{\text{D}}$ and $\overline{\text{INC}}$ inputs. HIGH to LOW transitions on $\overline{\text{INC}}$ will increment or decrement the wiper (depending on the state of the U/ $\overline{\text{D}}$ input and five-bit counter). The wiper, when at either fixed terminal, acts like its mechanical equivalent and does not move beyond the last position. When the CAT5115 is powered-down, the wiper position is reset. When power is restored, the counter is set to the mid point, tap 15.

Table 2. OPERATION MODES

INC	CS	U/D	Operation
High to Low	Low	High	Wiper toward H
High to Low	Low	Low	Wiper toward L
High	Low to High	Х	Store Wiper Position
Low	Low to High	Х	No Store, Return to Standby
Х	High	Х	Standby

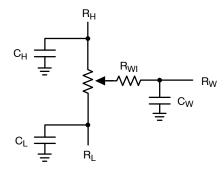


Figure 4. Potentiometer Equivalent Circuit

Table 3. ABSOLUTE MAXIMUM RATINGS

Parameters	Ratings	Units
Supply Voltage V _{CC} to GND	-0.5 to +7	V
Inputs CS to GND	-0.5 to V _{CC} +0.5	V
INC to GND	-0.5 to V _{CC} +0.5	V
U/D to GND	-0.5 to V _{CC} +0.5	V
H to GND	-0.5 to V _{CC} +0.5	V
L to GND	-0.5 to V _{CC} +0.5	V
W to GND	-0.5 to V _{CC} +0.5	V
Operating Ambient Temperature Industrial ('i' suffix)	-40 to +85	°C
Junction Temperature	+150	°C
Storage Temperature	-65 to 150	°C
Lead Soldering (10 s max)	+300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. RELIABILITY CHARACTERISTICS

Symbol	Parameter	Test Method	Min	Тур	Max	Units
V _{ZAP} (Note 1)	ESD Susceptibility	MIL-STD-883, Test Method 3015	2000			V
I _{LTH} (Notes 1, 2)	Latch-up	JEDEC Standard 17	100			mA
T _{DR}	Data Retention	MIL-STD-883, Test Method 1008	100			Years
N _{END}	Endurance	MIL-STD-883, Test Method 1003	1,000,000			Stores

- 1. This parameter is tested initially and after a design or process change that affects the parameter.
- 2. Latch-up protection is provided for stresses up to 100 mA on address and data pins from -1 V to V_{CC} + 1 V.

Table 5. DC ELECTRICAL CHARACTERISTICS (V_{CC} = +2.5 V to +6 V unless otherwise specified)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
POWER SUPPL	Y					
V _{CC}	Operating Voltage Range		2.5	_	6.0	V
I _{CC1}	Supply Current (Increment)	V _{CC} = 6 V, f = 1 MHz, I _W = 0	_	-	100	μΑ
		V _{CC} = 6 V, f = 250 kHz, I _W = 0	_	-	50	μΑ
I _{SB1} (Note 4)	Supply Current (Standby)	$\overline{\text{CS}} = \text{V}_{\text{CC}} - 0.3 \text{ V}$ U/ $\overline{\text{D}}$, $\overline{\text{INC}} = \text{V}_{\text{CC}} - 0.3 \text{ V}$ or GND	-	0.01	1	μΑ
LOGIC INPUTS	•	•	•			•
I _{IH}	Input Leakage Current	V _{IN} = V _{CC}	-	_	10	μΑ
I _{IL}	Input Leakage Current	V _{IN} = 0 V	_	-	-10	μΑ
V _{IH1}	TTL High Level Input Voltage	4.5 V ≤ V _{CC} ≤ 5.5 V	2	-	V _{CC}	V
V _{IL1}	TTL Low Level Input Voltage		0	-	0.8	V
V _{IH2}	CMOS High Level Input Voltage	$2.5 \text{ V} \leq \text{V}_{CC} \leq 6 \text{ V}$	V _{CC} x 0.7	-	V _{CC} + 0.3	V
V _{IL2}	CMOS Low Level Input Voltage		-0.3	-	V _{CC} x 0.2	V
POTENTIOMET	ER CHARACTERISTICS					-
R _{POT}	Potentiometer Resistance	-10 Device		10		kΩ
		-50 Device		50		
		-00 Device		100		
	Pot. Resistance Tolerance				±20	%
V_{RH}	Voltage on R _H pin		0		V _{CC}	V
V_{RL}	Voltage on R _L pin		0		V _{CC}	V
	Resolution			3.2		%
INL	Integral Linearity Error	I _W ≤ 2 μA		0.5	1	LSB
DNL	Differential Linearity Error	$I_W \le 2 \mu A$		0.25	0.5	LSB
R _{WI}	Wiper Resistance	V _{CC} = 5 V, I _W = 1 mA		70	200	Ω
		V _{CC} = 2.5 V, I _W = 1 mA		150	400	Ω
I _W	Wiper Current	(1)			1	mA
TC _{RPOT}	TC of Pot Resistance			±50	±300	ppm/°C
TC _{RATIO}	Ratiometric TC				20	ppm/°C
V _N	Noise	100 kHz / 1 kHz		8/24		nV/√Hz
C _H /C _L /C _W	Potentiometer Capacitances			8/8/25		pF
fc	Frequency Response	Passive Attenuator, 10 kΩ		1.7		MHz

This parameter is tested initially and after a design or process change that affects the parameter.
 Latch-up protection is provided for stresses up to 100 mA on address and data pins from –1 V to V_{CC} + 1 V.
 I_W = source or sink.
 These parameters are periodically sampled and are not 100% tested.

Table 6. AC TEST CONDITIONS

V _{CC} Range	$2.5~V \leq V_{CC} \leq 6.0~V$
Input Pulse Levels	0.2 x V _{CC} to 0.7 x V _{CC}
Input Rise and Fall Times	10 ns
Input Reference Levels	0.5 x V _{CC}

Table 7. AC OPERATING CHARACTERISTICS (V_{CC} = +2.5 V to +6.0 V, V_H = V_{CC} , V_L = 0 V, unless otherwise specified)

	(00 2 1		<u> </u>		
Symbol	Parameter	Min	Typ (Note 7)	Max	Units
t _{CI}	CS to INC Setup	100	-	-	ns
t _{DI}	U/D to INC Setup	50	-	-	ns
t _{ID}	U/D to INC Hold	100	-	-	ns
t _{IL}	ĪNC LOW Period	250	-	-	ns
t _{IH}	INC HIGH Period	250	-	-	ns
t _{IC}	INC Inactive to CS Inactive	1	-	-	μs
t _{CPH}	CS Deselect Time	100	-	-	ns
t _{IW}	INC to V _{OUT} Change	-	1	5	μs
t _{CYC}	INC Cycle Time	1	_	1	μs
t _R , t _F (Note 8)	INC Input Rise and Fall Time	_	_	500	μs
t _{PU} (Note 8)	Power-up to Wiper Stable	_	_	1	ms

- Typical values are for T_A = 25°C and nominal supply voltage.
 This parameter is periodically sampled and not 100% tested.
 MI in the A.C. Timing diagram refers to the minimum incremental change in the W output due to a change in the wiper position.

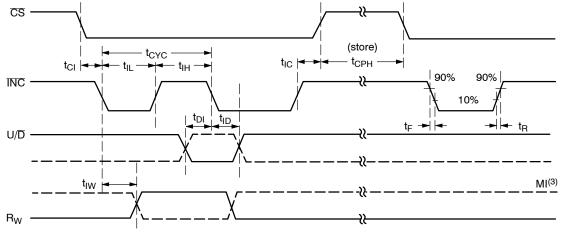


Figure 5. A.C. Timing

APPLICATIONS INFORMATION

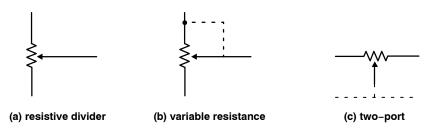


Figure 6. Potentiometer Configuration

Applications

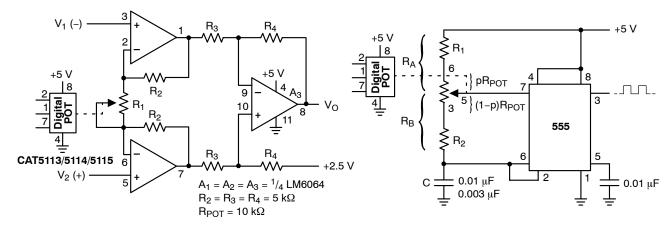


Figure 7. Programmable Instrumentation Amplifier

Figure 8. Programmable Sq. Wave Oscillator (555)

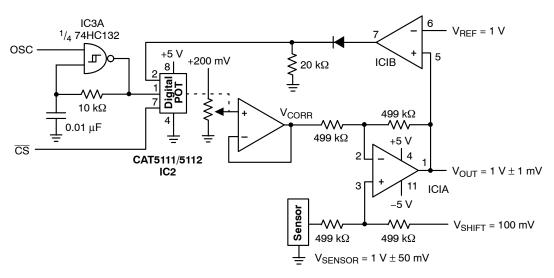


Figure 9. Sensor Auto Referencing Circuit

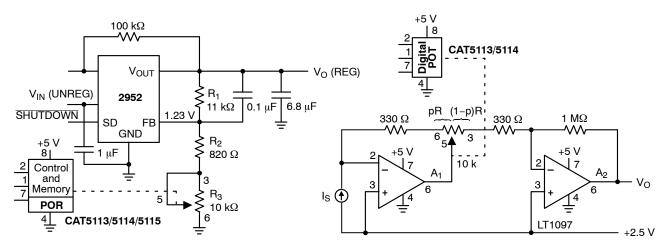


Figure 10. Programmable Voltage Regulator

Figure 11. Programmable I to V Convertor

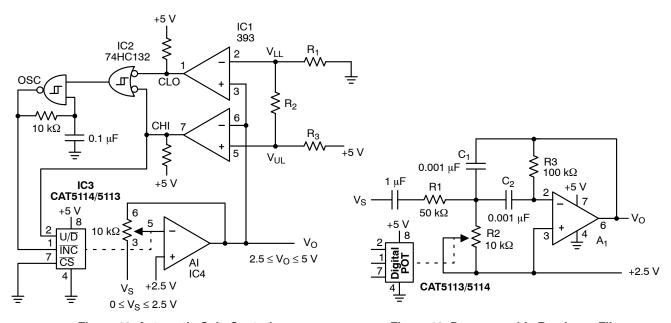


Figure 12. Automatic Gain Control

Figure 13. Programmable Bandpass Filter

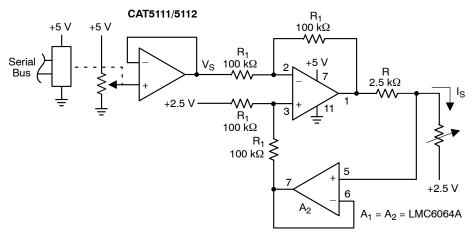


Figure 14. Programmable Current Source/Sink

Table 8. ORDERING INFORMATION

Orderable Part Numbers	Reset Threshold Voltage	Package-Pin	Lead Finish	Shipping [†]
CAT5115LI-10-G	10			50 Units / Tube
CAT5115LI-50-G	50	PDIP-8	NiPdAu	50 Units / Tube
CAT5115LI-00-G	100			50 Units / Tube
CAT5115VI-10-GT3	10			3000 / Tape & Reel
CAT5115VI-50-GT3	50	SOIC-8	NiPdAu	3000 / Tape & Reel
CAT5115VI-00-GT3	100			3000 / Tape & Reel
CAT5115YI-10-GT3	10			3000 / Tape & Reel
CAT5115YI-50-GT3	50	TSSOP-8	NiPdAu	3000 / Tape & Reel
CAT5115YI-00-GT3	100			3000 / Tape & Reel
CAT5115ZI-10-GT3	10			3000 / Tape & Reel
CAT5115ZI-50-GT3	50	MSOP-8	NiPdAu	3000 / Tape & Reel
CAT5115ZI-00-GT3	100			3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

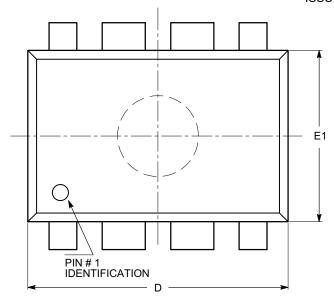
^{10.} For detailed information and a breakdown of device nomenclature and numbering systems, please see the ON Semiconductor Device Nomenclature document, TND310/D, available at www.onsemi.com.

^{11.} Contact factory for package availability.
12. All packages are RoHS-compliant (Lead-free, Halogen-free).
13. The standard lead finish is NiPdAu.

^{14.} For additional package and temperature options, please contact your nearest onsemi Sales office.

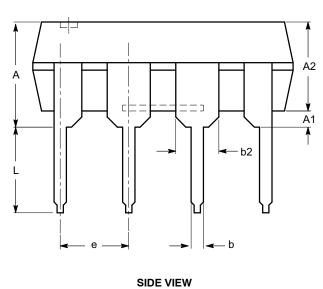
PACKAGE DIMENSIONS

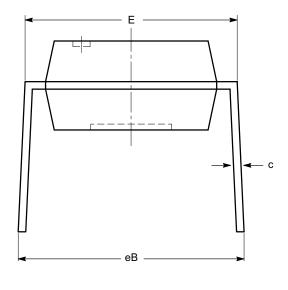
PDIP-8, 300 mils CASE 646AA ISSUE A



SYMBOL	MIN	NOM	MAX	
Α			5.33	
A1	0.38			
A2	2.92	3.30	4.95	
b	0.36	0.46	0.56	
b2	1.14	1.52	1.78	
С	0.20	0.25	0.36	
D	9.02	9.27	10.16	
Е	7.62	7.87	8.25	
E1	6.10	6.35	7.11	
е	2.54 BSC			
eB	7.87		10.92	
L	2.92	3.30	3.80	

TOP VIEW





END VIEW

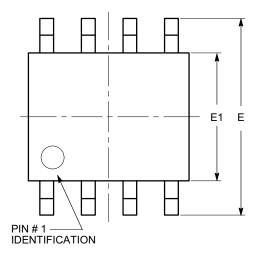
Notes:

- (1) All dimensions are in millimeters.(2) Complies with JEDEC MS-001.



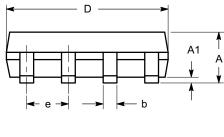
SOIC-8, 150 mils CASE 751BD ISSUE O

DATE 19 DEC 2008

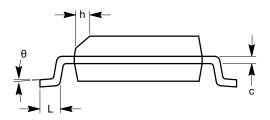


SYMBOL	MIN	NOM	MAX
Α	1.35		1.75
A1	0.10		0.25
b	0.33		0.51
С	0.19		0.25
D	4.80		5.00
Е	5.80		6.20
E1	3.80		4.00
е		1.27 BSC	
h	0.25		0.50
L	0.40		1.27
θ	0°		8°

TOP VIEW







END VIEW

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-012.

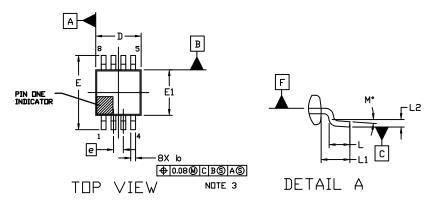
DOCUMENT NUMBER:	98AON34272E	Electronic versions are uncontrolled except when accessed directly from the Document Reprinted versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOIC 8, 150 MILS		PAGE 1 OF 1	

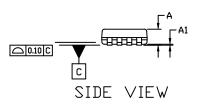
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MSOP8 3.0x3.0 CASE 846AQ ISSUE O

DATE 22 SEP 2020





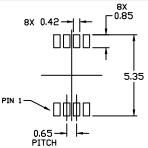


END VIEW

NUTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.10 mm IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- 4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 mm PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 mm PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
- 5. DATUMS A AND B ARE TO BE DETERMINED AT DATUM F.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 7. PIN 1 INDICATOR IS LOCATED HERE. MAY APPEAR AS A LASER MARKED, OR A MOLDED (CIRCLE OR HALF MODN), INDENT.

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α			1.10	
A1	0.03	0.08	0.18	
b	0.22	0.30	0.38	
c	0.105	0.125	0.195	
D	2.90	3.00	3.10	
Ε	4.65	4.90	5.15	
E1	2.90	3.00	3.10	
e		0.65 BSC	;	
L	0.30			
L1	0.95 REF			
L2	0.25 REF			
М	0*		10°	



RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the IN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	MSOP8 3.0x3.0		PAGE 1 OF 1	

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В NOTE 7





NDTES 5 & 6

E1

Δ2

PIN 1

REFERENCE

8X

TSSOP8, 4.4x3.0, 0.65P CASE 948AL **ISSUE A**

DATE 20 MAY 2022

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5, 2009..

 CONTROLLING DIMENSION: MILLIMETERS
 DIMENSION IN DIMENSION: MILLIMETERS
 DIMENSION IN DIMENSION: MILLIMETERS
 DIMENSION IN DIMENSION IN EXCESS DE MAXIMUM MATERIAL
 CONDITION.

 DIMENSION DI DIES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE
 BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED
 0.15 PER SIDE.

 DIMENSION EI DIES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
 THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM.
 DIMENSIONS DIE AND EI ARE DETERMINED AT THE OUTERMOST EXTREMES OF
 THE PLASTIC BODY AT DATUM PLANE H.
 DATUMS A AND B ARE TO BE DETERMINED AT DATUM H.
 DIMENSIONS DIE AND CAPPLY TO THE FLAT SECTION OF THE LEAD
 BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP..

 AI IS DEFINED AS THE LOWEST VERTICAL DISTANCE FROM THE SEATING
 PLANE TO THE LOWEST POINT ON THE PACKAGE BODY..



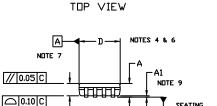
△ 0.15 C B S

29IT 8

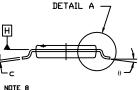
2X

♦ 0.10**M** C BS AS

8X b



SIDE VIEW



END VIEW

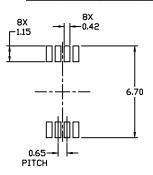
	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α			1.20	
A1	0.05		0.15	
A2	0.80	0.90	1.05	
b	0.19		0.30	
C	0.09		0.20	
D	2.90	3.00	3.10	
E	6.30	6.40	6.50	
E1	4.30	4.40	4.50	
e	0.65 BSC			
L	1.00 REF			
L1	0.50	0.60	0.70	
θ	0*		8•	

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Year WW = Work Week Α = Assembly Location = Pb-Free Package



RECOMMENDED MOUNTING FOOTPRINT*

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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